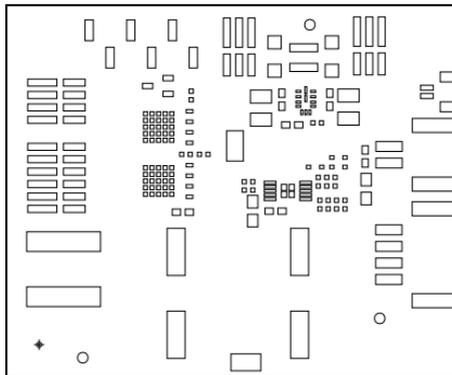
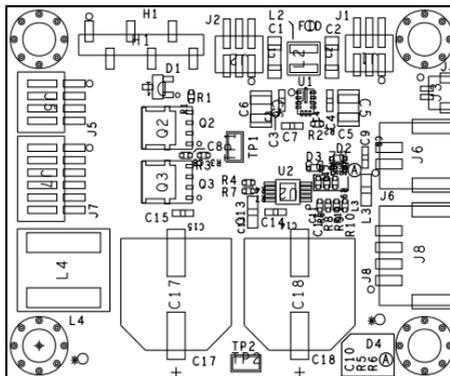


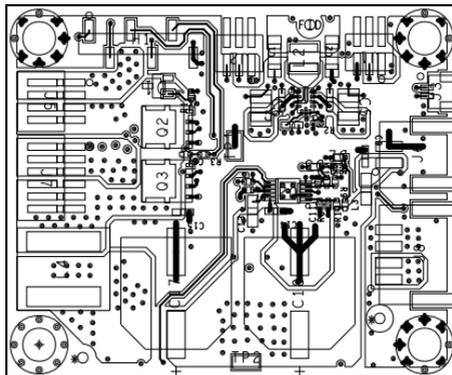
BOARD NAME: DLP034A_DLP5534Q1EVM_405MM_DRIVER_PCB	DESCRIPTION: SOLDERMASK - TOP SIDE	
PROJECT #: DLP5534-Q1_405MM_DRIVER	DATE: 09-AUG-2019	REVISION: A



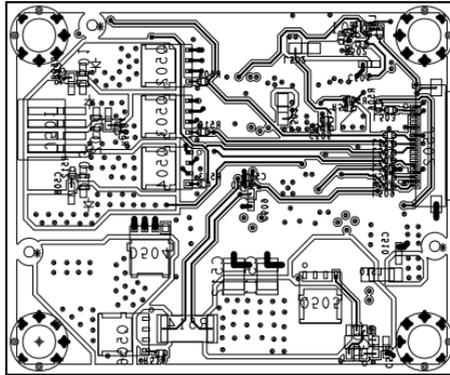
BOARD NAME: DLP034A_DLP5534Q1EVM_405MM_DRIVER_PCB	DESCRIPTION: SOLDERPASTE - TOP SIDE	
PROJECT #: DLP5534-Q1_405MM_DRIVER	DATE: 09-AUG-2019	REVISION: A



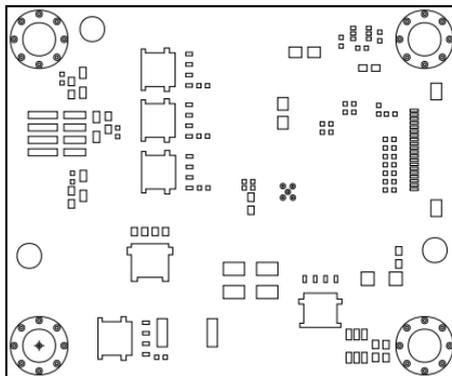
BOARD NAME: DLP034A_DLP5534Q1EVM_405MM_DRIVER_PCB			DESCRIPTION: ASSEMBLY - TOP SIDE		
PROJECT #: DLP5534-Q1_405MM_DRIVER		DATE: 09-AUG-2019		REVISION: A	



BOARD NAME: DLP034A_DLP5534Q1EVM_405MM_DRIVER_PCB	DESCRIPTION: LAYER 01 - TOP SIDE	
PROJECT #: DLP5534-Q1_405MM_DRIVER	DATE: 09-AUG-2019	REVISION: A

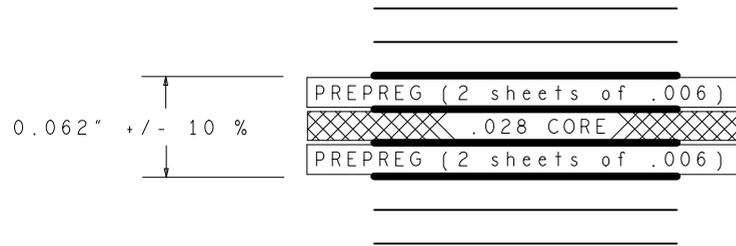


BOARD NAME: DLP034A_DLP5534Q1EVM_405MM_DRIVER_PCB	DESCRIPTION: LAYER 04 - BOTTOM SIDE	
PROJECT #: DLP5534-Q1_405MM_DRIVER	DATE: 09-AUG-2019	REVISION: A



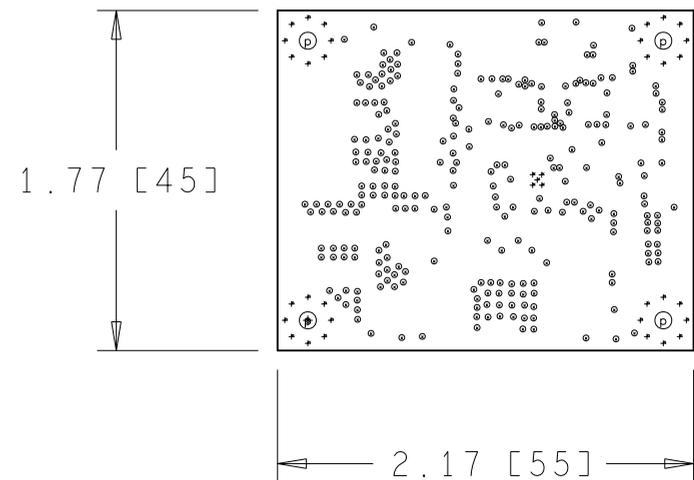
BOARD NAME: DLP034A_DLP5534Q1EVM_405MM_DRIVER_PCB	DESCRIPTION: SOLDERMASK - BOTTOM SIDE	
PROJECT #: DLP5534-Q1_405MM_DRIVER	DATE: 09-AUG-2019	REVISION: A

LAYER STACKUP



LAYER DEFINITION	FINISH Cu WT.
SILKSCREEN PRIMARY SIDE	
SOLDERMASK PRIMARY SIDE	
LAYER 1 PRIMARY SIDE	2 oz
LAYER 2 (GND PLANE)	2 oz
LAYER 3 (PWR SPLIT PLANE)	2 oz
LAYER 4 SECONDARY SIDE	2 oz
SOLDERMASK SECONDARY SIDE	
SILKSCREEN SECONDARY SIDE	

THIS IN A NON-IMPEDANCE CONTROLLED BOARD



COMPONENT SIDE SHOWN

ALL DIMENSIONS ARE IN INCHES [mm]

BOARD NAME: DLP034A_DLP5534Q1EVM_405MM_DRIVER_PCB		DESCRIPTION: FAB LAYER	
PROJECT #:	DLP5534-Q1_405MM_DRIVER	DATE:	09-AUG-2019
		REVISION:	A

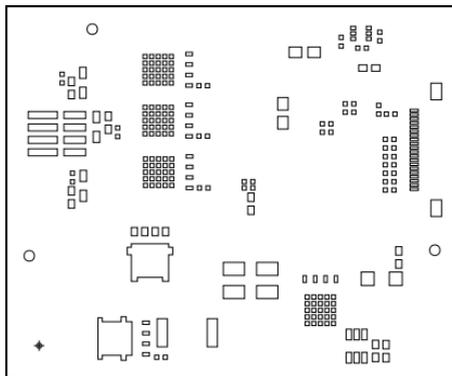
FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES UNLESS OTHERWISE NOTED. ALL BOARD OUTLINE DIMENSION TOLERANCES ARE +/- .010".
- THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
- BOARD MATERIAL SHALL BE 180 Tg/340 Td ISOLA FR-370HR OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. RoHS CERTIFICATE OF CONFORMANCE SHALL BE DELIVERED WITH EACH LOT.
- BOARD MATERIALS AND CONSTRUCTION TO BE WITH UL94V-0 APPROVED. FINISHED BOARD TO BE MARKED WITH UL94-V0 AND E_FILE NUMBER.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .001 INCH.
- OVERALL BOARD THICKNESS TO BE .062 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.

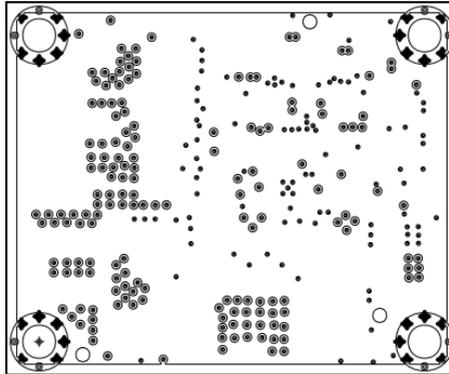
PROCESS NOTES:

- PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 100 MIN MICROINCHES THK GOLD 2-6 MICROINCHES THK.
- APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC), COLOR: GREEN. SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV. VIA TENTING FOLLOW AS PER ARTWORK.
- FABRICATION VENDOR IS ALLOWED TO INCREASE SOLDERMASK COMPONENT PADS BY A MAXIMUM 1 MIL ON EACH SIDE OVER THE COPPER PAD IN ORDER TO MEET TOOLING REQUIREMENTS WHILE MAINTAINING WEBBING BETWEEN ADJACENT PADS.
- APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.

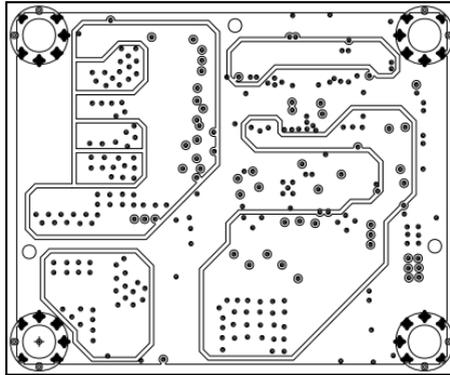
DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	10.0	+0.0/-10.0	PLATED	267
*	10.1	+0.0/-10.0	PLATED	5
*	14.0	+3.0/-3.0	PLATED	32
⊙	157.0	+3.0/-3.0	PLATED	4



BOARD NAME: DLP034A_DLP5534Q1EVM_405MM_DRIVER_PCB	DESCRIPTION: SOLDERPASTE - BOTTOM SIDE	
PROJECT #: DLP5534-Q1_405MM_DRIVER	DATE: 09-AUG-2019	REVISION: A



BOARD NAME: DLP034A_DLP5534Q1EVM_405MM_DRIVER_PCB	DESCRIPTION: LAYER 02 - GND PLANE	
PROJECT #: DLP5534-Q1_405MM_DRIVER	DATE: 09-AUG-2019	REVISION: A



BOARD NAME: DLP034A_DLP5534Q1EVM_405MM_DRIVER_PCB	DESCRIPTION: LAYER 03 - PWR SPLIT PLANE	
PROJECT #: DLP5534-Q1_405MM_DRIVER	DATE: 09-AUG-2019	REVISION: A